

Polar3™ HiPerFET™ **Power MOSFET**

IXFK98N50P3 IXFX98N50P3

N-Channel Enhancement Mode Avalanche Rated Fast Intrinsic Diode

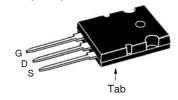


Symbol	Test Conditions	Maximum	Ratings
V _{DSS}	$T_J = 25$ °C to 150°C	500	V
V _{DGR}	$T_J = 25$ °C to 150°C, $R_{GS} = 1M\Omega$	500	
V _{GSS}	Continuous	± 30	V
V _{GSM}	Transient	± 40	
I _{D25}	$T_{\rm C} = 25^{\circ}{\rm C}$	98	A
	$T_{\rm C} = 25^{\circ}{\rm C}$, Pulse Width Limited by $T_{\rm JM}$	245	A
I _A	$T_{c} = 25^{\circ}C$	49	A
E _{AS}	$T_{c} = 25^{\circ}C$	4.5	J
P _D	T _C = 25°C	1300	W
dv/dt	$I_{S} \le I_{DM}, V_{DD} \le V_{DSS}, T_{J} \le 150^{\circ}C$	35	V/ns
T _J		-55 +150	ာ
T _{JM}		150	၁
T _{stg}		-55 +150	၁
T _L	Maximum Lead Temperature for Soldering	300	°C
T _{SOLD}	Plastic Body for 10s	260	°C
M _d	Mounting Torque (TO-264)	1.13/10	Nm/lb.in
F _c	Mounting Force (PLUS247)	20120 /4.527	N/lb
Weight	TO-264	10	g
	PLUS247	6	g

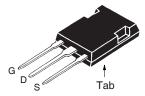
Symbol (T _J = 25°C U	ymbol Test Conditions Γ _J = 25°C Unless Otherwise Specified)		Characteristic Values Min. Typ. Max.		
BV _{DSS}	$V_{GS} = 0V, I_D = 3mA$	500			V
$V_{\rm GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 8mA$	3.0		5.0	V
l _{gss}	$V_{GS} = \pm 30V$, $V_{DS} = 0V$			± 200	nA
I _{DSS}	$V_{DS} = V_{DSS}$, $V_{GS} = 0V$ $T_{J} = 125^{\circ}C$	C		25 1.5	μA mA
R _{DS(on)}	$V_{GS} = 10V, I_{D} = 0.5 \cdot I_{D25}, Note 1$			50	mΩ

500V **98A** D25 = $\mathbf{R}_{\mathrm{DS(on)}}$ $50m\Omega$ ≤ 250ns ≤

TO-264 (IXFK)



PLUS247 (IXFX)



G = Gate D = Drain S = SourceTab = Drain

Features

- Dynamic dv/dt Rating
- Avalanche Rated
- Fast Intrinsic Diode
- Low Q_G
- Low R_{DS(on)}
 Low Drain-to-Tab Capacitance
- Low Package Inductance

Advantages

- Easy to Mount
- Space Savings

Applications

- DC-DC Converters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- Uninterrupted Power Supplies
- AC Motor Drives
- High Speed Power Switching **Applications**

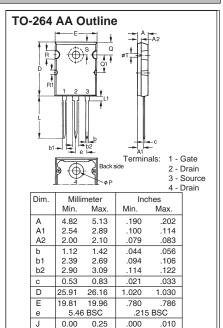


Symbo		Test Conditions		cteristic '	
$(T_{J} = 25)$	5°C U	nless Otherwise Specified)	Min.	Тур.	Max.
g_{fs}		$V_{DS} = 10V, I_{D} = 0.5 \bullet I_{D25}, Note 1$	55	90	S
C _{iss})			12.9	nF
\mathbf{C}_{oss}	}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		1300	pF
C _{rss}	J			11	pF
R _{Gi}		Gate Input Resistance		1.2	Ω
t _{d(on)})	Resistive Switching Times		48	ns
t _r	Ţ	$V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 0.5 \cdot I_{D25}$		21	ns
$\mathbf{t}_{d(off)}$	($R_{\rm G} = 10$ (External)		90	ns
t,	J	n _g = 152 (External)		12	ns
$\mathbf{Q}_{g(on)}$)			200	nC
\mathbf{Q}_{gs}	}	$V_{gs} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 0.5 \cdot I_{D25}$		63	nC
\mathbf{Q}_{gd}	J			62	nC
R _{thJC}					0.096 °C/W
R _{thCS}				0.15	°C/W

Source-Drain Diode

Symbo	I Test Conditions	Characteristic Values			
$(T_J = 25)$	s°C, Unless Otherwise Specified)	Min.	Тур.	Max.	
I _s	$V_{GS} = 0V$			98	Α
I _{SM}	Repetitive, Pulse Width Limited by T_{JM}			390	Α
V _{SD}	$I_F = I_S$, $V_{GS} = 0V$, Note 1			1.5	V
t _{rr}	I _E = 49A, -di/dt = 100A/μs			250	ns
\mathbf{Q}_{RM})		1.6		μC
I _{RM}	$V_{R} = 100V, V_{GS} = 0V$		15.4		Α

Note 1. Pulse test, $t \le 300\mu s$, duty cycle, $d \le 2\%$.



PLUS 247™ Outline

0.00

20.32

2.29

3.17

6.07

8.38

3.81

1.78

6.04

1.57

0.25

20.83

2.59

3.66

6.27

8.69

4.32

2.29

6.30

1.83

.010

.820

.102

.144

.247

.342

.170

.090

.248

.072

.000

.800

.090

.125

.239

.330

.150

.070

.238

.062

K

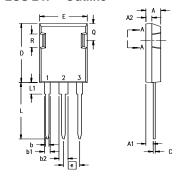
L L1

Р

Q

R

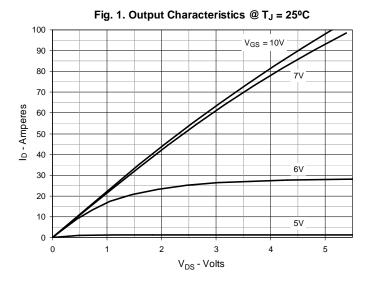
Q1

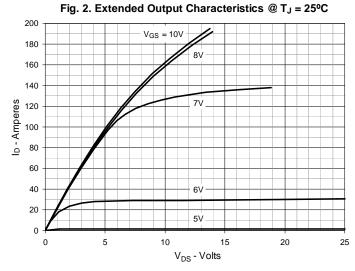


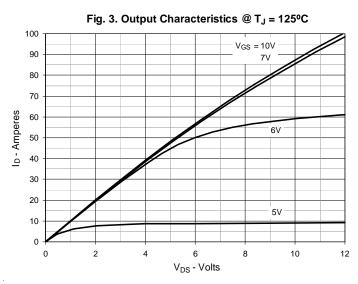
1 - Gate Terminals: 2 - Drain 3 - Source

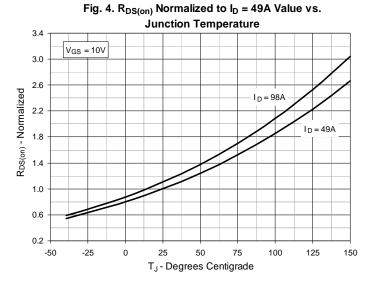
Milli	meter	Inches		
Min.	Max.	Min.	Max.	
4.83	5.21	.190	.205	
2.29	2.54	.090	.100	
1.91	2.16	.075	.085	
1.14	1.40	.045	.055	
1.91	2.13	.075	.084	
2.92	3.12	.115	.123	
0.61	0.80	.024	.031	
20.80	21.34	.819	.840	
15.75	16.13	.620	.635	
5.45	BSC	.215 BSC		
19.81	20.32	.780	.800	
3.81	4.32	.150	.170	
5.59	6.20	.220	0.244	
4.32	4.83	.170	.190	
	Min. 4.83 2.29 1.91 1.14 1.91 2.92 0.61 20.80 15.75 5.45 19.81 3.81 5.59	4.83 5.21 2.29 2.54 1.91 2.16 1.14 1.40 1.91 2.13 2.92 3.12 0.61 0.80 20.80 21.34 15.75 16.13 5.45 BSC 19.81 20.32 3.81 4.32	Min. Max. Min. 4.83 5.21 .190 2.29 2.54 .090 1.91 2.16 .075 1.14 1.40 .045 1.91 2.13 .075 2.92 3.12 .115 0.61 0.80 .024 20.80 21.34 .819 15.75 16.13 .620 5.45 BSC .215 19.81 20.32 .780 3.81 4.32 .150 5.59 6.20 .220	

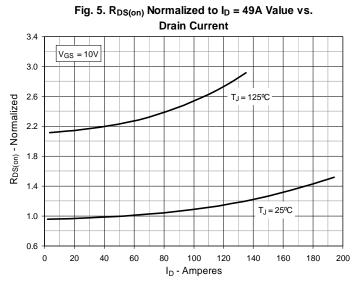


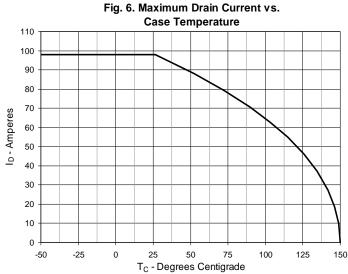




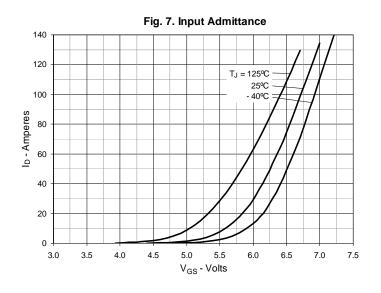


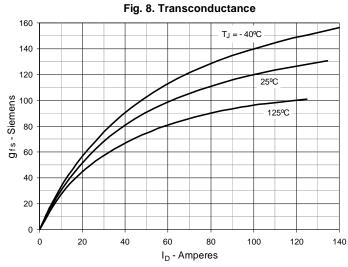


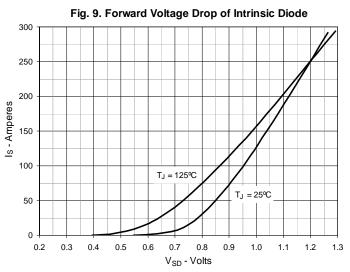


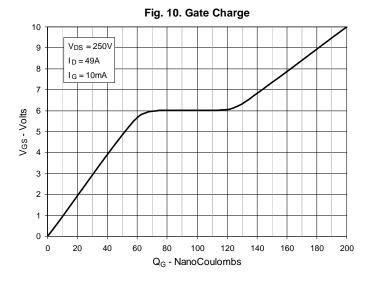


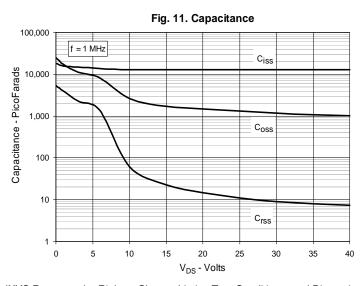


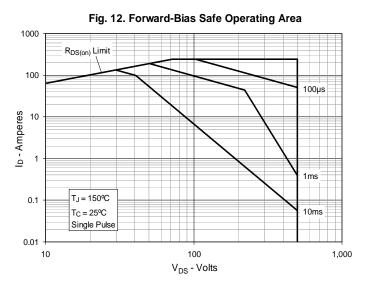












 $\ensuremath{\mathsf{IXYS}}$ Reserves the Right to Change Limits, Test Conditions, and Dimensions.

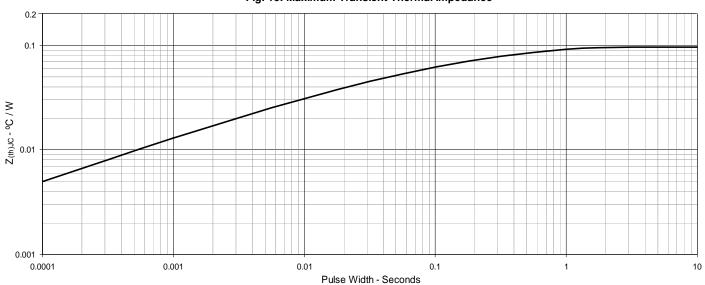


Fig. 13. Maximum Transient Thermal Impedance

